I CLAIM:

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- 1. A water soluble hot melt blocking composition for contact lens manufacture, the composition comprising:
 - (a) about 5 to 95 wt% of a water soluble polymer composition; and
 - (b) about 1 to about 50 wt% of a highly water soluble micronized salt comprising a sodium or potassium salt of a strong acid, the salt having a particle size of less than about 150 microns.
- 10 2. The composition of claim 1 wherein the salt comprises a sodium chloride, potassium chloride or mixtures thereof and the particle size of the salt is less than 90 microns.
- 3. The composition of claim 1 wherein the water-soluble polymer comprises a cellulosic polymer in an amount of about 15 to 75 wt.%.
 - 4. The composition of claim 1 wherein the polymer comprises a poly(ethyleneglycol) in an amount of about 15 to 75 wt.%.
- 5. The composition of claim 1 wherein the water-soluble polymer comprises a poly (vinyl pyrrolidone) in an amount of about 15 to 75 wt.%.
 - 6. The composition of claim 1 wherein the particle size is about 20 to 80 microns.
- The composition of claim 1 additionally comprising a surfactant.
 - 8. The composition of claim 1 wherein the composition comprises about 10-50 wt% of a hydroxy substituted organic compound.
- 30 9. The composition of claim 7 wherein the hydroxy substituted organic compound comprises hydroxywax.

- 10. A water-soluble hot melt blocking composition for contact lens manufacture, the composition comprising:
 - (a) about 25-50 wt% of a water soluble alkyl substituted polyethyleneimine polymer; and
 - (c) about 5 to about 50 wt% of a water soluble sodium or potassium salt of a strong acid.
- 11. The composition of claim 10 additionally comprising about 10-50 wt% of a hydroxy substituted organic compound comprising a hydroxywax having hydroxy number of greater than 150.
 - 12. The composition of claim 10 wherein the alkyl substituted polyethyleneimine polymer comprises a compound of the formula:

wherein R is a C_{1-5} alkyl, m is about 50-10,000.

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- 13. The composition of claim 10 wherein there is about 25 to 40 wt% of the water soluble polymer, about 15 to 45 wt% of a hydroxywax and about 15 to 45 wt% of a water soluble micronized sodium chloride or potassium chloride salt.
 - 14. The composition of claim 10 more in the particle size is less than about 150 microns.
 - 15. The composition of claim 10 additionally comprising a surfactant.

- 16. The composition of claim 10 wherein the composition comprises about 10-50 wt% of a hydroxy substituted organic compound.
- 17. The composition of claim 16 wherein the hydroxy substituted organic5 compound comprises hydroxywax.

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- 18. A water soluble hot melt blocking composition for contact lens manufacture, the composition comprising:
 - (a) about 5 90 wt% of a water soluble polymer composition;
 - (b) about 1 50 wt% of a hydroxy substituted organic compound; and
- (c) about 1 50 wt% of an inorganic filler material; wherein the components are blended such that the material is a structural solid at a temperature of less than about 130°F and wherein the material is substantially melt form at a temperature greater than 140°F.
- 19. The composition of claim 18 wherein the composition is a solid at less than 120°F.
- 20. The composition of claim 18 wherein the composition is a melt at a temperature greater than 165°F.
 - 21. The composition of claim 18 wherein the hydroxy substituted organic compound comprises about 5-50 wt% of a hydroxy wax.
- 25 22. The composition of claim 18 wherein the water-soluble polymer comprises an alkyl substituted polyethyleneimine polymer comprising a compound of the formula:

-[CH₂CH₂-N]_m-

wherein R is a C_{1-5} alkyl, m is about 50-10,000 and is present in an amount of about 15 to 75 wt.%.

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- 23. The composition of claim 18 wherein the inorganic filler comprises a sodium or potassium salt of a strong acid.
- 24. The composition of claim 18 wherein the water-soluble polymer comprises a polyethyl oxazoline polymer having a molecular weight of about 10,000 to 500,000 and is present in an amount of about 15 to 45 wt.%.
 - 25. The composition of claim 18 wherein the inorganic filler comprises a particle size less than about 150 microns.

- 26. The composition of claim 18 wherein the hydroxy substituted organic compound has a hydroxy number of greater than 150.
- 27. The composition of claim 18 wherein the composition comprises a
- 20 surfactant.